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Including this transmittal sheet, document consists of <u>43</u> pages.

Date: July 15, 2004

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nts From: Christopher S. Daly, Esq.

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MESSAGE

Re: U.S. Patent Application of Rafael Reif et al.

Application No.: 10/655,854

Entitled: MULTI-LAYER INTEGRATED SEMICONDUCTOR STRUCTURE

Filed On: September 5, 2003 DCM Case No.: MIT-136AUS

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	Application Number	10/655,854				
TRANSMITTAL	Filing Date	September 5, 2003				
FORM	First Named Inventor	Rafael Reif				
(to be used for all correspondence after initial filing)	Art Unit	2811				
	Examiner Name	Not Yet Assigned				
Total Number of Peges in This Submission 42	Attorney Docket Number	MIT-136AUS				
ENCLOSURES (Check all that apply)						
Fee Transmittal Form	Assignment Papers for an Application)	After Allowance communication to Technology Center (TC) Appeal Communication to Board				
Fee Atteched)rawing(s)	Appeal Communication to Board of Appeals and Interferences				
Amendment/Reply	icensing-related Papers	Appeal Communication to TC (Appeal Notice, Brief, Reply Brief)				
	etition	Proprietary Information				
	etition to Convert to a rovisional Application	Status Letter				
Extension of Time Request	ower of Attorney, Revocation hange of Correspondence Address	Other Enclosure(s) (please identify below):				
Express Abandonment Request Information Disclosure Statement	erminal Discleimer	Return Postcard PTO SB/08A with Eight (8) References				
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Document(s)	CD, Number of CD(s)					
Response to Missing Parts/ Incomplete Application		ļ ,				
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under 37 CFR 1.52 or 1.53 In the every provided	ent a petition for extension of time , such petition is hereby made and eposit account No. 50-0845 for the	is required by this paper and not otherwise if authorization is provided herewith to				
	F APPLICANT, ATTORNEY, C					
Firm Christopher S. Daly		ACHOLIN				
Individual name Daly, Crowley & Mofford	_ •					
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Typed or printed name Christopher S	. Daly					
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PATENT

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Appl. No.

10/655,854

Confirmation No.: 7254

JUL 1 9 2004

Applicant

Rafael Reif et al. September 5, 2003

Filed T.C./A.U.

2811

Examiner

: Not Yet Assigned

Docket No.

: MIT-136AUS

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Christopher \$! Daly

Reg. No. 37,303

INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

It is desired to cite for the record in this application the enclosed documents listed on the attached copy of PTO form PTO/SB/08A (Formerly #1449). The paragraph(s) marked below are applicable to this Information Disclosure Statement.

The enclosed Information Disclosure Statement is being filed: within three [X] (1) months of the filing date; or within three months of the entry of the national stage of the aboveidentified application; or before the mailing of a first Office Action on the merits; or before the mailing of a first Office Action after the filing of a request for continued examination under 37 C.F.R. §1.114. Accordingly, Applicant(s) believes that no fee or statement is required.

Page 1 of 5

Docket No. MIT-136AUS

[] (2) Pursuant to 37 C.F.R. § 1.97(c), the enclosed Information Disclosure Statement is being filed before the mailing date of a final action or a notice of allowance and is accompanied by the fee set forth in 37 C.F.R. § 1.17(p).

SUBMISSION UNDER 37 C.F.R. § 1.97(c) INCLUDING A STATEMENT UNDER 37 C.F.R. § 1.97(e)(1)

[] (3) Pursuant to 37 C.F.R. § 1.97(c), the enclosed Information Disclosure Statement is being filed before the mailing date of a final action or a notice of allowance and is accompanied by a statement under 37 C.F.R. § 1.97(e)(1). The undersigned hereby states that each item of information contained in the attached Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application mailed not more than three months prior to the filing of the accompanying Information Disclosure Statement.

SUBMISSION UNDER 37 C.F.R. § 1.97(c) INCLUDING A STATEMENT UNDER 37 C.F.R. § 1. 97(e)(2)

[] (4) Pursuant to 37 C.F.R. § 1.97(c), the enclosed Information Disclosure Statement is being filed before the mailing date of a final action or a notice of allowance and is accompanied by a statement under 37 C.F.R. § 1.97(e)(2). The undersigned hereby states that no item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to any individual having a duty of disclosure as set forth in 37 C.F.R. § 1.56 (c) more than three months prior to the filing of the accompanying Information Disclosure Statement.

Docket No. MIT-136AUS

SUBMISSION UNDER 37 C.F.R. § 1.97(c)

INCLUDING STATEMENTS UNDER 37 C.F.R. §§ 1.704(d) AND 1.97(e)(1)

[] (5) Pursuant to 37 C.F.R. § 1.97(c), the enclosed Information Disclosure Statement is being filed before the mailing date of a final action or a notice of allowance and is accompanied by statements under 37 C.F.R. §§ 1.704(d) and 1.97(e)(1). The undersigned hereby states that each item of information contained in the attached Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application mailed not more than three months prior to the filing of the accompanying Information Disclosure Statement and was not received by any individual designated in §1.56(c) more than thirty days prior to the filing of the accompanying Information Disclosure Statement.

SUBMISSION UNDER 37 C.F.R. § 1.97(d) INCLUDING A STATEMENT UNDER 37 C.F.R. §1.97(e)(1)

[] (6) Pursuant to 37 C.F.R. § 1.97(d), the enclosed Information Disclosure Statement is being filed on or before payment of the issue fee and is accompanied by a statement under 37 C.F.R. § 1.97(e)(1) and the fee required under 37 C.F.R. § 1.17(p). The undersigned hereby states that each item of information contained in the accompanying Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

SUBMISSION UNDER 37 C.F.R. § 1.97(d) INCLUDING A STATEMENT UNDER 37 C.F.R. §1.97(e)(2)

[] (7) Pursuant to 37 C.F.R. § 1.97(d), the enclosed Information Disclosure Statement is being filed on or before payment of the issue fee and is accompanied by a statement under 37 C.F.R. § 1.97(e)(2) and the fee required under 37 C.F.R. § 1.17(p). The undersigned hereby states that no item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to

Docket No. MIT-136AUS

any individual having a duty of disclosure as set forth in 37 C.F.R. § 1.56(c) more than three months prior to the filing of the accompanying Information Disclosure Statement.

SUBMISSION UNDER 37 C.F.R. § 1.97(d) INCLUDING STATEMENTS UNDER 37 C.F.R. §§ 1.704(d) AND 1.97(e)(1)

[] (8) Pursuant to 37 C.F.R. § 1.97(d), the enclosed Information Disclosure Statement is being filed on or before payment of the issue fee and is accompanied by statements under 37 C.F.R. §§ 1.704(d) and 1.97(e)(1) and the fee required under 37 C.F.R. § 1.17(p). The undersigned hereby states that each item of information contained in the attached Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application mailed not more than three months prior to the filing of the accompanying Information Disclosure Statement and was not received by any individual designated in §1.56(c) more than thirty days prior to the filing of the accompanying Information Disclosure Statement.

The filing of this Information Disclosure Statement is not a representation by the undersigned as to personal knowledge of the contents of every word or phrase of the material enclosed or that reliance on other suitably trained professionals has not been made.

If a search report of a searching agency is enclosed identifying the nature of the relevance of each document, such a designation is deemed to satisfy Rule 98(a) (3) even if in a foreign language, since the few terms of relevance therein are deemed of universal cognizance. However, Applicant(s) does not necessarily adopt the position reflected by that report.

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The Commissioner is hereby authorized to charge payment of any additional fees associated with this communication or credit any overpayment to Deposit Account No. 500845.

Dated: 1900L04

Respectfully submitted,

DALY, CROWLEY & MOFFORD, LL

Christopher S. Daly

Reg. No. 27,303 Attorney for Applicant(s)

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PTO/SB/08B (02-03)

Approved for use through 04/30/2003. OMB 0651-0031 U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

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		Application Number	10/655,854		
INFORMATION DISCL	.OSURE	Filing Date	September 5, 2003		
STATEMENT BY APPLICANT		First Named Inventor	Rafael Reif		
		Art Unit	2811		
(Use as many sheets as necessary)		Examiner Name	Not Yet Assigned		
Sheet 1 of	1	Attorney Docket Number	MIT-136AUS	1	

Examiner	Cite	OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of	
Examiner Initials*	No.1	the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		OSAMU TABATA, Anisotropic Etching of Silicon in TMAH Solutions, Toyota Central Research and Development Laboratories, Inc., February 21, 1992, Pages 51-57, Japan	
		PHILIP M. SAILER, Creating 3D Circuits Using Transferred Films, Cicuits & Devices, November 1997, Pages 27-30	
		TAKUJ MATSUMOTO, New Three-Dimensional Wafer Bonding Technology Using the Adhesive Injection Method, March, 1998, Pages 1217-1221, Jpn. J. Appl. Phys. Vol. 37 (1998)	
		A. FAN, Copper Wafer Bonding, Electrochemical and Solid-State Letters, 1999, Pages 534-536, Cambridge, Massachusetts	
		ARIFUR RAHMAN, Wire-Length Distribution of Three-Dimensional Integrated Circuits, 1999, Pages 233-235	
		VICTOR W.C. CHAN, Three Dimensional CMOS Integrated Circuits on Large Grain Polysillicon Films, EEE, Hong Kong University of Science and Technology, 2000, Pages 00-161 - 00-164 Hong Kong	
		K.W. LEE, Three-Dimensional Shared Memory Fabricated Using Wafer Stacking Technology, Dept. of Machine Intelligence and Systems Engineering, 2000, Pages 00-165 - 00-168, Hong Kong	
	-	KUAN-NENG CHEN, Microstructure Examination of Copper Wafer Bonding, Microsystem Technology Laboratories, December 20, 2000, Pages 331-335, Cambridge, Massachusetts	
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Examiner	Date	
Signature	 Considered	

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^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

1 Applicant's unique citation designation number (optional). 2 Applicant is to piece a check mark here if English language Translation is attached.

This collection of Information is required by 87 CFR 1.98. The Information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.O. 122 and 37 CFR 1.14. This collection is estimated to take 120 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will very depending upon the Individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commiscs, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: MIS Amendment, Commissioner for Patents, P. O. Box 1450. Alexandria, VA 22313-1450. MS Amendment, Commissioner for Patents, P. O. Box 1450, Alexandria, VA 22313-1450.